

### **General Description**

The WST2066 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST2066 meet the RoHS and Green Product requirement with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

### **Product Summery**

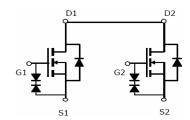
BVDSS	RDSON	ID		
20V	16mΩ	7.2A		

### **Applications**

- Power management in portable and battery operated products
- One cell battery pack protection
- ESD:2KV

### **SOT-23-6L Pin Configuration**





### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	20	V	
$V_{GS}$	Gate-Source Voltage	±12	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	7.2	Α	
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	5.8	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	Α	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>3</sup>	1.4	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 15		$^{\circ}\!\mathbb{C}$	
$T_J$	Operating Junction Temperature Range -55 to 150		°C	

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		150	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		70	°C/W

## Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.028		V/°C
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =6.7A		16	18	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =2.5V , I <sub>D</sub> =5.2A		20	25	mΩ
		V <sub>GS</sub> =1.8V , I <sub>D</sub> =3A		30	40	
V <sub>GS(th)</sub>	Gate Threshold Voltage	\/ -\/     -250uA	0.3	0.6	1.5	1400
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-3.21		
	Drain-Source Leakage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
I <sub>DSS</sub>		$V_{DS}$ =16V , $V_{GS}$ =0V , $T_J$ =55 $^{\circ}$ C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm12V$ , $V_{DS}$ =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =5A		8		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		4	6	Ω
Qg	Total Gate Charge (4.5V)			13	17	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =10V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =6.7A		1.5	2.5	nC
$Q_gd$	Gate-Drain Charge			1.8	2.9	
T <sub>d(on)</sub>	Turn-On Delay Time			6.1		
T <sub>r</sub>	Rise Time	$V_{DD}$ =10V , $V_{GEN}$ =4.5V , $R_{G}$ =6 $\Omega$		9.7		ns
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1.0A ,RL=30Ω.		26		
T <sub>f</sub>	Fall Time			5.2		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V , V <sub>GS</sub> =0V , f=1MHz		610	725	
C <sub>oss</sub>	Output Capacitance			140	175	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			130	150	

### **Diode Characteristics**

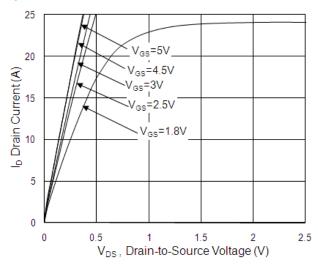
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V =V =0V Force Current			1.0	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			20	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>SD</sub> =1.3A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time			18		nS
Q <sub>rr</sub>	Reverse Recovery Charge	lF=6.7A,dI/dt=100A/μs , T <sub>J</sub> =25℃		12		nC

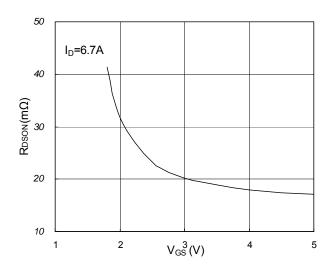
### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



### **Typical Characteristics**





**Fig.1 Typical Output Characteristics** 

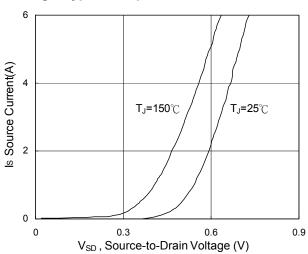


Fig.2 On-Resistance vs. Gate-Source

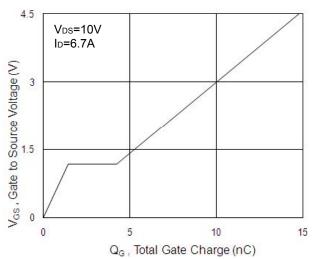


Fig.3 Forward Characteristics of reverse

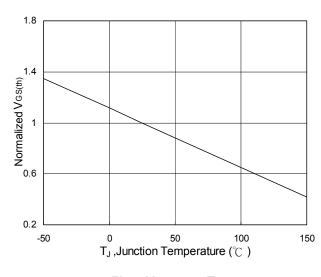


Fig.4 Gate-Charge Characteristics

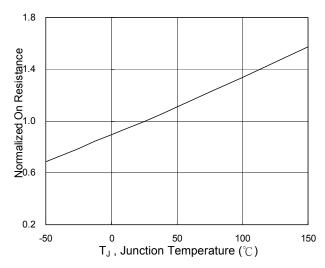
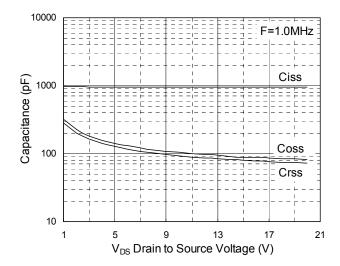


Fig.5 V<sub>GS(th)</sub> vs. T<sub>J</sub>

Fig.6 Normalized  $R_{\text{DSON}}$  vs.  $T_{\text{J}}$ 





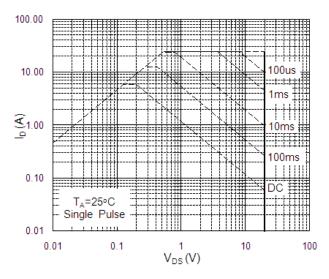


Fig.7 Capacitance

Fig.8 Safe Operating Area

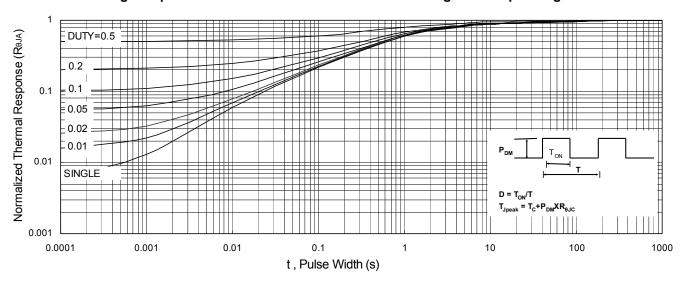


Fig.9 Normalized Maximum Transient Thermal Impedance

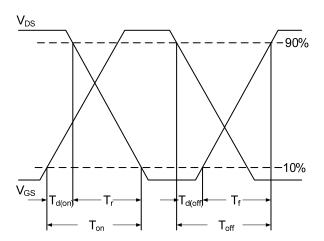


Fig.10 Switching Time Waveform

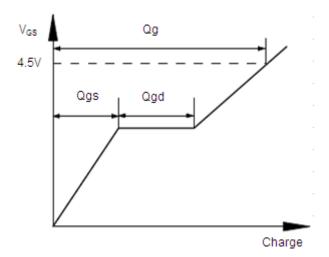


Fig.11 Gate Charge Waveform



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